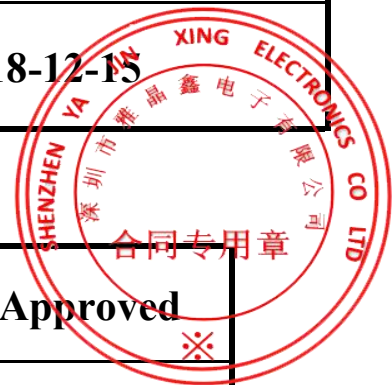


雅晶鑫電子

Shenzhen Yajingxin Electron Co.,Ltd

<b>Customer</b>	
<b>Production Name</b>	<b>SMD OCSECSC4R SEAM 7.0*5.0</b>
<b>Customer P/N</b>	<b>N/A</b>
<b>P/N</b>	<b>TFOM50M40ZKCNT2T</b>
<b>Revision</b>	<b>A</b>
<b>Print Date</b>	<b>2018-12-15</b>



<b>Drawn</b>	<b>Checked</b>	<b>Approved</b>

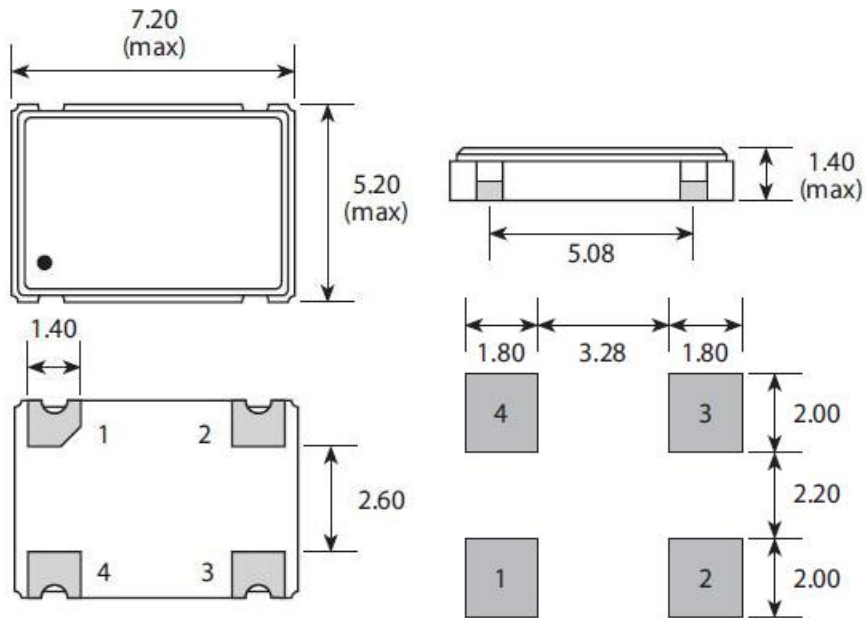
**RoHS Compliant**

## ■ Electrical Specifications

1.Model No	7050 OSC	
2.Nominal Frequency	50.000MHz	
3.Mode of Oscillation	3rd	
4.Operating Temperature Range	-40℃ to85℃	
5.Storage Temperature Range	-55℃ to +125℃	
6.Frequency Stability	±50ppm	
7.Power Supply Voltage	3.3V±10%	
8.Input Current	10mA Max. : 1.500- 32.000MHz 15mA Max. : 32.001- 50.000MHz 25mA Max. : 50.000- 70.000MHz 60mA Max. : 70.001- 125.00MHz	
9.Output Voltage	Logic High(Voh)	90%Vdd Min
	Logic Low(Vol)	10%Vdd Max
10.Output Load	15pF max CMOS Load	
11.Semmetry (at 50%VDD)	40-60%Normal	
12.Rise & Fall Time	8ns Max.	
13.E/D or N/C.	Tri-state	
14.Output Disable Time	100nsec	
15.Output Enable Time(start-up time)	10msec max	
16.Aging	±3ppm/year	
17.Unit Weight		

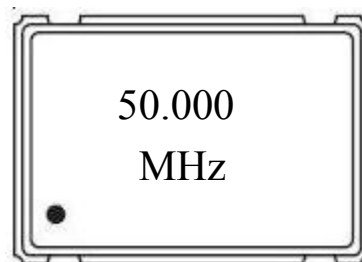
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■ Dimensions



Pad	1	2	3	4
Connection	N.C.(INH)	GND	OUTPUT	VDD

■ Marking

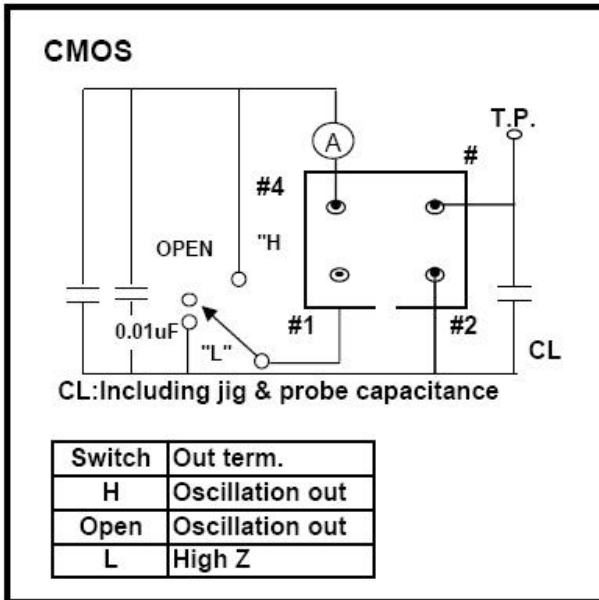


Line 1: 客户指定印字 →

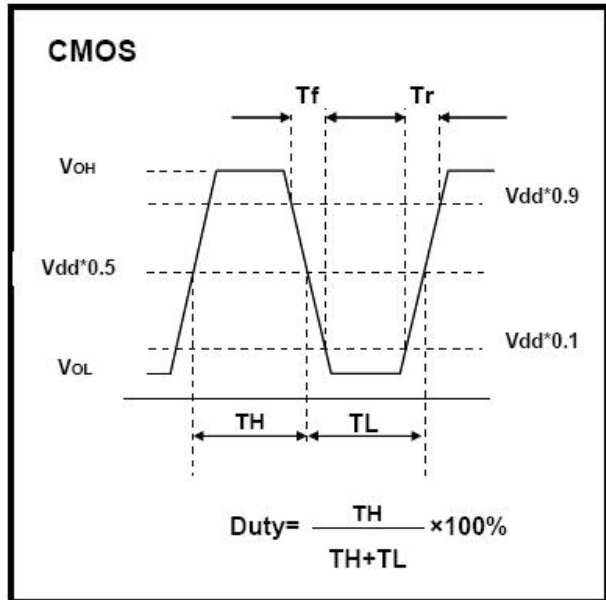
Line 2: ● → Pin#1 indication

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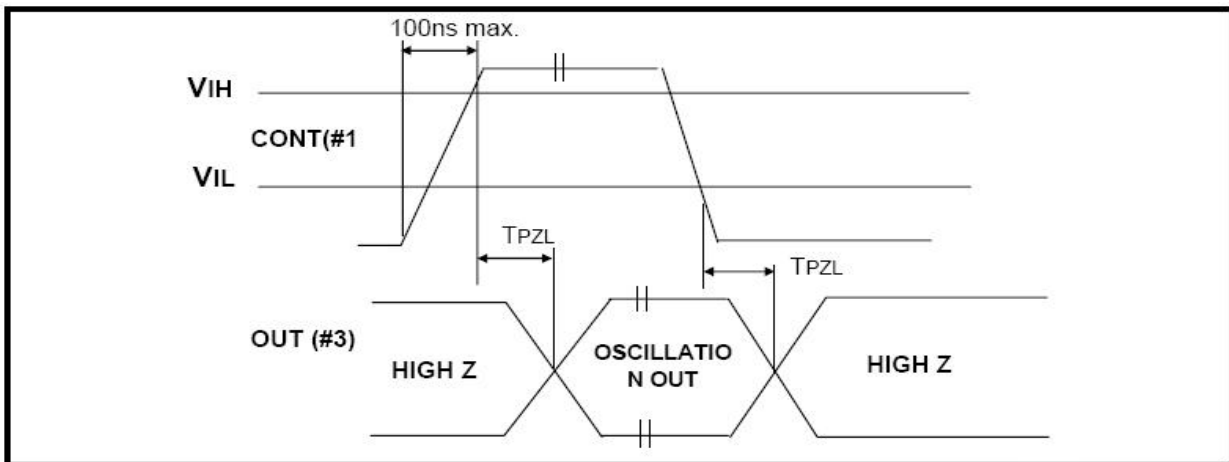
■ Measurement Circuit



Output Wave Form

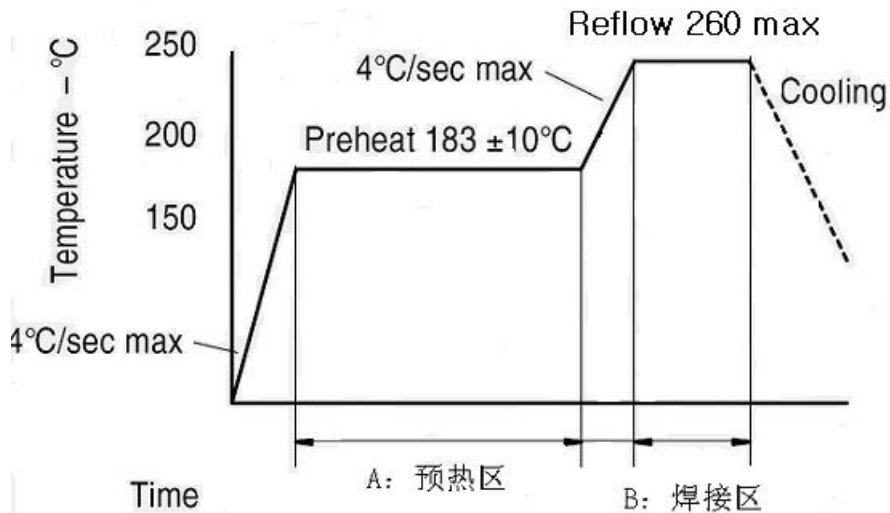


■ Input Output Condition



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■ Reflow Profile



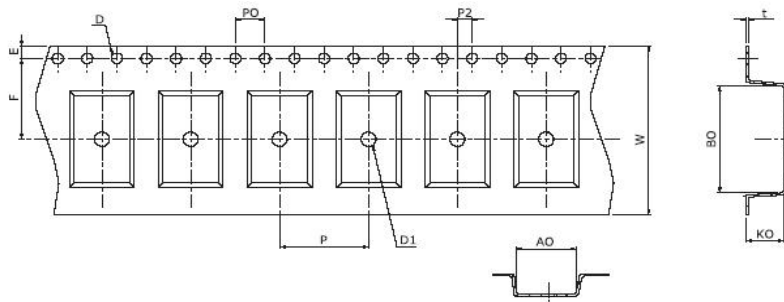
■ Reliability Specifications

No	Test Item	Test Methods
1	DROP TEST	Device are dropped from a height of 75 cm onto 3 mm thickness stainless plate executing 3 times of random drops.
2	MECHANICAL SHOCK	Device are shocked to half sine wave (1000 G) three mutually perpendicular axes each 3 times.
3	High Temp and Humidity Test	85°C/RH 85%, 500Hrs
4	High temp storage test	125°C+/-2°C 500Hrs
5	Low temp storage test	-40°C 500Hrs
6	Thermal shock test	-40°C~+85°C DWEL 60' 100cycles
7	Aging test	85°C 1000Hrs

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8	Resistance to solder heat	260°C 10S
9	VIBRATION	Frequency range 10-2000 Hz Amplitude Sweep 1.5 mm Sweep Time 20 minute Test Time 2 hours
10	SOLDERABILITY	MIL - STD - 20E Method 208C Temperature 245°C±5°C Material H63A (Silver 2-3 %) Immersion depth 0.5 mm minimum Immersion time 3 ± 0.5 seconds Flux Rosin resin methyl

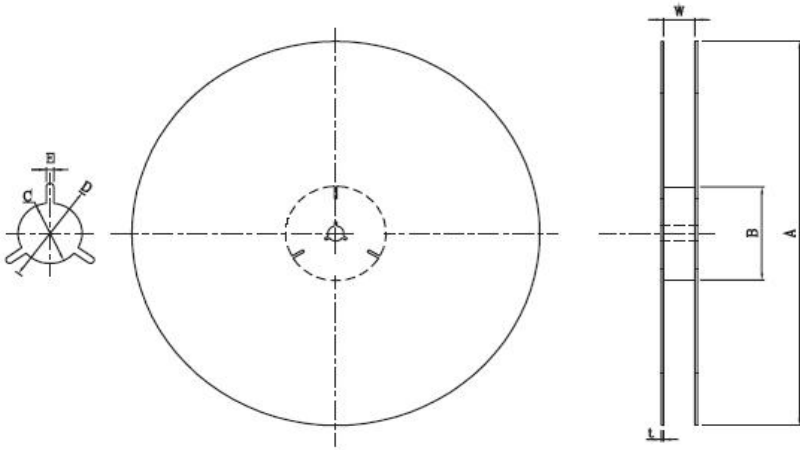
■ Packing



A0:5.40±0.1	B0:7.40±0.3	W:16.2±0.3	E1:1.75±0.1
P0: 4.0±0.1	P : 8.0±0.1	P2: 2.0±0.1	D: phi 1.50±0.1
F: 7.50±0.1	KO:1.90±0.1		

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■ Reel Dimension



A: $\phi 180 \pm 1.0$	B: $\phi 60 \pm 1.0$	C: $\phi 13.0 \pm 0.5$	D: $\phi 12.0 \pm 1.0$
E: $1.9 \pm 0.5$	W: $25.5 \pm 1.0$		

NOTE: 1. packgeing q'ty 1000PCS /REEL

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